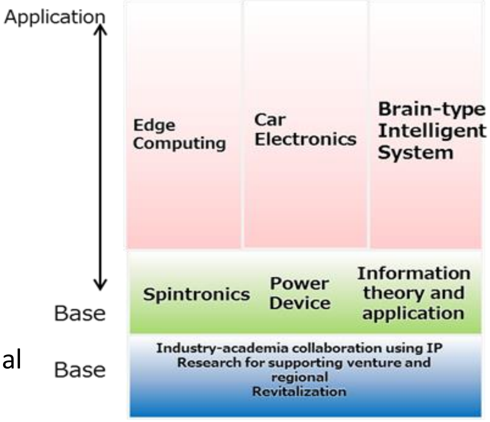
# Call for Proposals
# CIES Collaborative Research
# Center for Innovative Integrated Electronic Systems, Tohoku University

| | |
|---|---|
| Aim | CIES aims to contribute to the enhancement of global competitiveness in the field of next-generation integrated electronics systems, and work toward the creation of practical applications and new industries, through the research and development of innovative devices and its integrated electronic systems and the establishment of a consortium for this field under the international collaboration among industries, universities and government.<br>"CIES Collaborative Research" promotes advanced R&D with cooperation of the CIES researchers in wide range of fields from upstream (physics and economic theory, materials, process, device, etc.) to – downstream (system, application, and marketing, etc.) in the next-generation integrated electronics for accelerating the integration and innovation. |
| R&D areas | The proposals in the following priority R&D areas in CIES are applicable.<br>(1)Spintronics<br>(2)Power devices<br>(3) Information theory and its application<br>(4)Edge computing<br>(5)Car electronics<br>(6)Brain-type intelligent system<br>(7) Industry-academia collaboration using IPs, research for venture support and regional revitalization<br> |
| Support | Four types of research proposals are available. The research period of each type is for one year, and not only using CIES facilities but collaboration researches with CIES researchers are essential.<br>Type I：Proposal of industry-academic collaboration<br>Research theme for the purpose of developing it to an industry-academic collaboration.<br>R&D grant：2,000,000yen/year (It may be reduced depending on the review results)<br>Type II：Support for young researchers<br>Research theme for project leaders under 45 years old.<br>R&D grand：1,500,000yen/year(It may be reduced depending on the review results) |

| | |
|---|---|
| | Type III：Research meeting<br>Exploratory research theme<br>R&D grand：1,000,000yen/year (It may be reduced depending on the review results)<br>Type IV：Industry-university collaborative project using CIES facilities<br>Research theme for the purpose of developing it to a large-scale industry-academic collaboration.<br>R&D grant: Maximum 5,000,000yen/year (On this program, a supporting rate enforces it as 50% of matching fund. Please note that the supporting rate may become less than 50% when the total amount increases.) |
| Research period | From the adoption decision notice (Scheduled for June 2017) through March 31, 2018 |
| Possible candidates | Researchers who belong universities, national research institutes and private enterprises, etc. The university-academic collaborations or the international collaborations are preferable. Independent proposals from universities, research organizations and companies in Japan are acceptable. |
| Renewal | Renewable based on the same research project as the previous year, but the total research period is within three years. |
| Deadline for applications | May 1, 2017 (The proposals must arrive) ※Additional proposals might be accepted. |
| Result announcement | The middle of June, 2017 (tentative) |
| Application materials | The files of the following documents (pdf) should be sent to the following e-mail address and the printed-out documents should be sent via regular mail to the following address on the last page. Please note that the application documents will not be returned.<br>(1) Application form for CIES collaborative research<br>(2) Acceptance letter for CIES collaborative research (from your institute)<br><br>The result will be announced by CIES collaborative research selection committee.<br>When it is accepted, the project leader and co-researchers will be commissioned as “Collaborative researcher of Center for Innovative Integrated Electronic System, Tohoku University”. |
| Number of accepted proposals | Number of accepted proposals in FY2016<br>Type I：1 / Type II：2 / Type III：1 / Type IV：none |

| | |
|---|---|
| Others<br>(Results and report) | 1. The handling of intellectual property rights<br>Tohoku University Regulation regarding collaborative research will be applied as standard. [ http://www.rpip.tohoku.ac.jp/files/kyoudou.pdf ]<br>2. Expenses<br>Travel expenses in order to visit CIES for research and workshop, and the budget for promoting research will be provided. The amount will be decided depending on the number of accepted proposals.<br>3. Accommodation<br>Please arrange it by yourself as CIES has no facilities.<br>4. Submission of the research report<br>Project leader should submit a research report within 3 pages on A4 paper by March 31, 2018.<br>※The form will be sent to you later.<br>A hearing regarding Type IV will be held in the end of the fiscal year. It may be also organized for both Type I and II. Additionally a questionnaire will be excluded.<br>5. Acknowledgement<br>When you publish achievements of CIES Collaborative Research, please add the following sentences as acknowledgement. Please submit one copy to CIES.<br>(1) Part of this work was carried out under the CIES Collaborative Research of the Center for Innovative Integrated Electronic Systems, Tohoku University.<br>(2) This work was performed in the CIES Collaborative Research of the Center for Innovative Integrated Electronic Systems, Tohoku University.<br>(3) We acknowledge the stimulated discussion in the meeting of the CIES Collaborative Research of the Center for Innovative Integrated Electronic Systems, Tohoku University.<br>(4) This conference was partially supported by the CIES Collaborative Research of the Center for Innovative Integrated Electronic Systems, Tohoku University.<br>6. Presentation of achievements<br>CIES Collaborative Research accomplishments presentation will be held in the end of the fiscal year. We may request you to present the achievement.<br>7. The handling of R&D<br>R&D is one of the projects of CIES. Please follow the regulations of CIES during the term. |
| Contact | Strategic Planning Division<br>Center for Innovative Integrated Electronic Systems, Tohoku University<br>468-1 Aramaki Aza Aoba, Aoba-ku, Sendai, Miyagi 980-0845, JAPAN<br>E-mail: support-office@cies.tohoku.ac.jp<br>Tel：022-796-3410 Fax：022-796-3432 |